

Harvatek Surface Mount CHIP LED Data Sheet HT-311FDH

Official Product	HT Part No. HT-311FDH	Customer Part No.		Data Sheet No.
Tentative Product	*********	*******		HT-311FDH
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		June 19, 2009	Version of 1.0	Page 1/18



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DISCLAIMER

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- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- 2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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Product Specifications

	Specification	Material	Quantity
lv	Amber: 71.5-285.0 mcd		
	Green: 112.5-360.0 mcd		
	Blue: 71.5-285.0 mcd		
	@20mA/ Ta= 25 ^o C		
λD	Amber: 615-630 nm		
	Green: 515-540 nm		
	Blue: 470-485 nm		
	@20mA/ Ta= 25 ^o C		
Vf	Amber: 1.7-2.4 V		
	Green: 2.9-3.9 V		
	Blue: 2.0-3.9 V		
	@20mA/ Ta= 25 ^o C		
Ir	< 100 µA @ V _R = 5 V		
Resin	Diffused	Epoxy resin	
Carrier tape	EIA 481-1A specs	Conductive black tape	1000pcs per reel
Reel	EIA 481-1A specs	Conductive black	
Label	HT standard	Paper	
Packing bag	220x240mm	Aluminum laminated bag/ no-zipper	One reel per bag
Carton	HT standard	Paper	Non-specified

Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv, λ_D and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

ATTENTION: Electrostatic Discharge (ESD) protection



The symbol to the left denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AllnGaP, GaN, or/and InGaN based chips are **STATIC SENSITIVE devices**. ESD precaution must

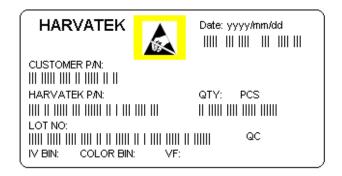
be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

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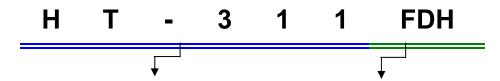


Label Specifications



■Customer P/N: To Be Defined

■ Harvatek P/N:



Series Name	Emitting Color	
HT-311	FDH	
3.2x1.5x1.0mm	Tri-color Amber, Green,	
3.2X1.5X1.UMM	and Blue @ 20mA	

Lot No.:

1 2 3 4 5 6 7 8 9 10 P 1 2 2 3 0 A - D T

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Code 1	Code 2	Code 3	Code 4, 5	Code 6, 7	Code 9	Code 10
	Mfg. Year	Mfg. Month	Mfg. Date	Lots	Resin Color	Packaging
		1: Jan.				
	Z: 2000	2: Feb.				
Internal	1: 2001			04 - 00		
Tracing	2: 2002	9: Sep.	1~31/ (30)	01~99,	D: Milky White	T: Tape & Reel
Code	3: 2003	A: Oct.		A,B,C		
		B: Nov.				
		C: Dec.				

■ Luminous Intensity (Iv) Bin:

Color	Bin Code	Spec. Range
	Q	71.5-112.5 mcd
Amber	R	112.5-180.0 mcd
	S	180.0-285.0 mcd
	R	112.5-180.0mcd
Green	S	180.0-285.0 mcd
	Т	285.0-360.0 mcd
	Q	71.5-112.5 mcd
Blue	R	112.5-180.0 mcd
	S	180.0-285.0 mcd

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■ Dominant Wavelength (λ_D) Bin:

Color	Bin Code	Spec. Range
	В	600-603 nm
Amber	С	603-606 nm
Allibei	D	606-609 nm
	E	609-612 nm
	AB	515-525 nm
Green	CD	525-535 nm
	E	535-540 nm
	С	470-475 nm
Blue	D	475-480 nm
	E	480-485 nm

■ Forward Voltage (Vf) Bin:

Color	Bin Code	Spec. Range
Amber	-	1.7-2.4 V
Green	-	2.9-3.9 V
Blue	-	2.9-3.9 V

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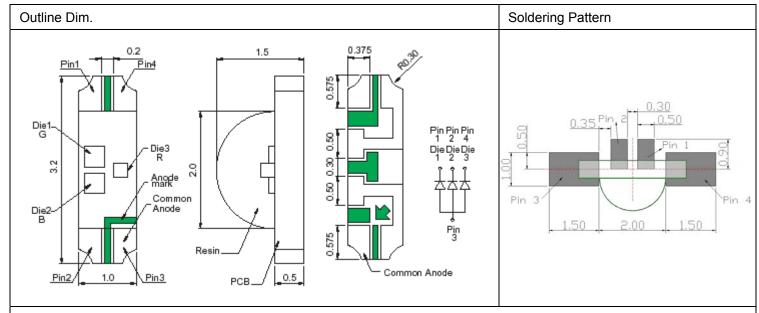
Product Feature

Electro-Optical Characteristics

Code for parts Lighting Color		$V_F(V)$		λ (nm)			I [*] _V (mcd)		
Code for parts	arts Lighting Color		typ	max	λ _D	λ _P	$\triangle \lambda$	Typical	
	Die3	Ultra Bright Amber	UD	1.9	2.4	605	609	17	180
HT-311FDH	Die1	Green	NG	3.3	3.9	527	520	40	240
	Die2	Blue	NB	3.3	3.9	470	468	26	180

Package Outline Dimension and Recommended Soldering Pattern for Reflow Soldering

Unit: mm Tolerance: +/-0.1



- -Soldering terminals may shift in the x, y direction.
- -Common anode.

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Absolute Maximum Ratings

(Ta 25 °C)

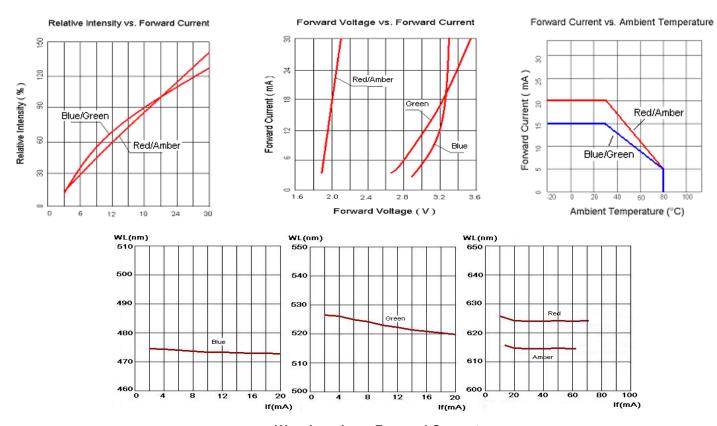
Series	P _d (mW)	I _F (mA)	I _{FP} (mA)	V _R (V)	I _R (uA)	T _{OP} (°C)	T _{ST} (°C)
Amber	46	20	100	5	<100@ V = 5	·30~+80	-40~+85
Blue/Green	74	20	80	5	<100@ V _R = 5	-30'3+80	-40**85

^{**} Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width

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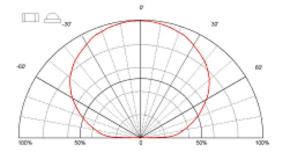


Characteristics of HT-311FDH

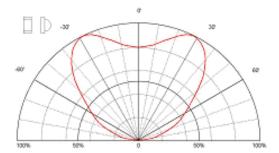


Wavelength vs. Forward Current





Directive Characteristics

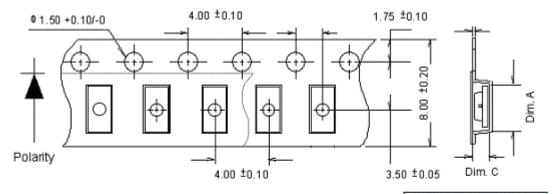


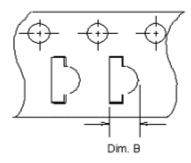
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Packaging

Tape Dimension





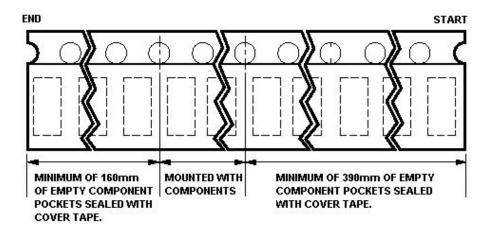
- Polarity referring onto the cathode mark is reversed on the UR (N side-up chips).
- The carrier tape and components loading specifications meet the EIA 481-1A Standard.

Part No.	Dim. A	Dim. B	Dim. C	Q'ty/Reel
HT-311	3.40±0.10	1.70±0.10	1.20±0.10	1K

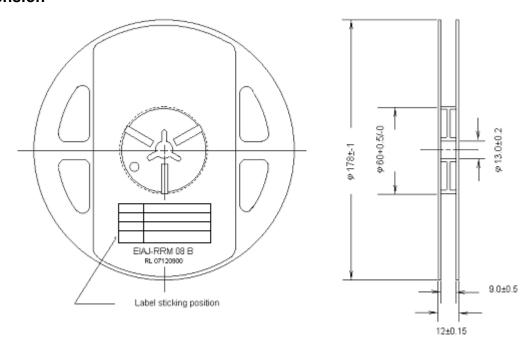
Unit: mm

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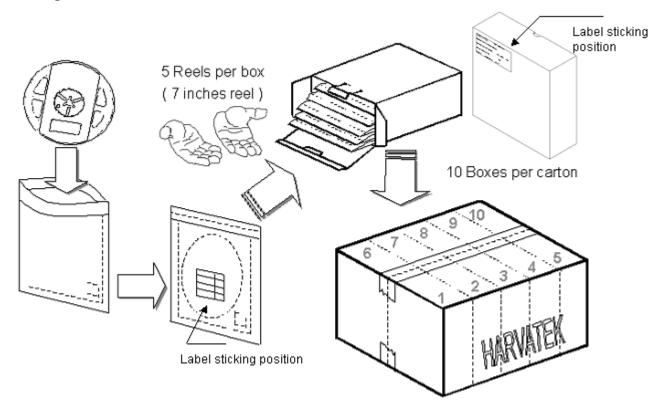
Reel Dimension



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Packing



5 boxes per carton is available depending on shipment quantity.

Dry Pack

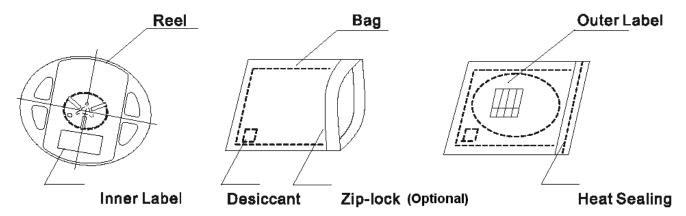
All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

Upon request, a humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

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The packaging sequence is as follows:



PRECAUTIONS

- 1. Avoid exposure to moisture at all times during transportation or storage.
- 2. Anti-Static precaution must be taken when handling GaN, InGaN, and AllnGaP products.
- 3. It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage beyond the specified limit.
- 4. Avoid operation beyond the limits as specified by the absolute maximum ratings.
- 5. Avoid direct contact with the surface through which the LED emits light.
- 6. If possible, assemble the unit in a clean room or dust-free environment.

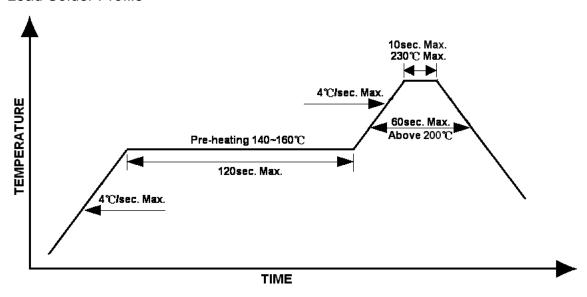
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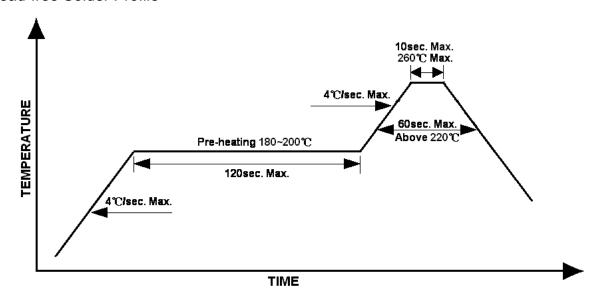
Reflow Soldering

- Recommended tin glue specifications: melting temperature in the range of 178~192 OC
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

Lead Solder Profile



Lead-free Solder Profile



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Reworking

- Rework should be completed within 5 seconds under 260 °C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultra sonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 °C max, <3min

Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electric-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

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Reliability

Item	Frequency/ lots/ samples/ failures	Standards Reference	Conditions
Precondition	For all reliability monitoring tests according to JEDEC Level 2	J-STD-020	1.) Baking at 85°C for 24hrs 2.) Moisture storage at 85°C/ 60% R.H. for 168hrs
Solderability	1Q/ 1/ 22/ 0	JESD22-B102-B And CNS-5068	Accelerated aging 155°C/ 24hrs Tinning speed: 2.5±0.5cm/s Tinning: A: 215°C/ 3±1s or B: 260°C/ 10±1s
Resistance to soldering heat		CNS-5067	Dipping soldering terminal only Soldering bath temperature A: 260+/-5°C; 10+/-1s B: 350+/-10°C; 3+/-0.5s
Operating life test	1Q/ 1/ 40/ 0	CNS-11829	1.) Precondition: 85°C baking for 24hrs 85°C/ 60%R.H. for 168hrs 2.) T _{amb} 25°C; I _F =20mA; duration 1000hrs
High humidity, high temperature bias	1Q/ 1/ 45/ 0	JESD-A101-B	T _{amb} : 85°C Humidity: 85% R.H., I _F =5mA Duration: 1000hrs
High temperature bias	1Q/ 1/ 20	HT specs.	T _{amb} : 55°C I _F =20mA Duration: 1000hrs
Pulse life test	1Q/ 1/ 40/ 0		$T_{amb}25$ °C, I_f =20mA,, I_p =100mA, Duty cycle=0.125 (tp=125 μ s,T=1sec) Duration 500hrs)
Temperature cycle	1Q/ 1/ 76/ 0	JESD-A104-A IEC 68-2-14, Nb	A cycle: -40 degree C 15min; +85 degree C 15min Thermal steady within 5 min 300 cycles 2 chamber/ Air-to-air type
High humidity storage test	1Q/ 1/ 40/ 0	CNS-6117	60±3°C 90+5/-10% R.H. for 500hrs
High temperature storage test	1Q/ 1/ 40/ 0	CNS-554	100±10°C for 500hrs
Low temperature storage test	1Q/ 1/ 40/ 0	CNS-6118	-40 <u>+</u> 5°C for 500hrs

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Revision History

Changes since last revision	Page	Version No.	Revision Date
New Format		1.0	06-19-2009

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